

Welcome to O-leading

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service - S/S in 24hrs , 4-8layers in 48-96 working hrs production time.

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

PLEASE CLICK THESE FOR MORE INFORMATION [Engine Power Module manufacturer china](#)

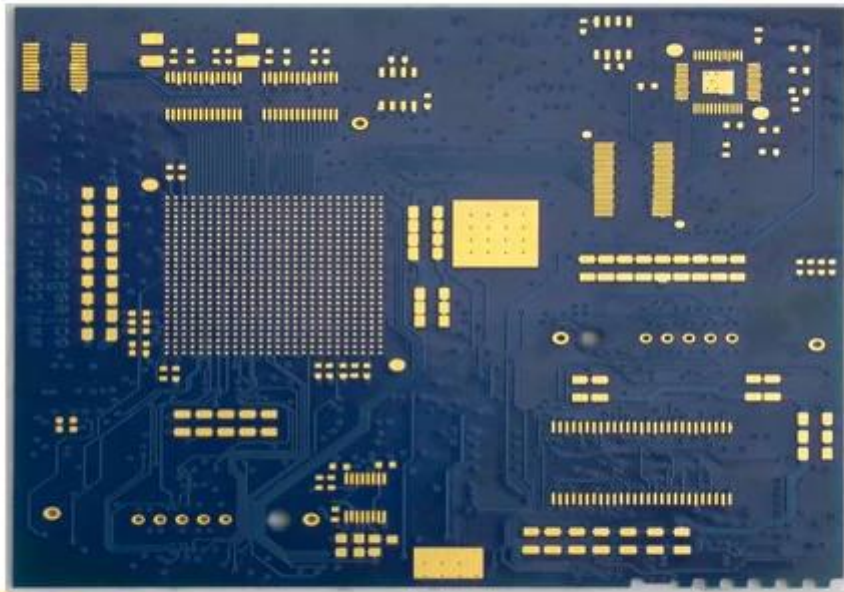
Product Description

Quick Details

Place of Origin	Guang dong, China (Mainland)	Brand Name	O-Leading
Model Number	power bank pcb assembly pcba manufacturer	Base Material	FR-4,,Aluminum
Copper Thickness	0.5oz-5oz	Board Thickness	0.1-5mm
Surface Finishing	immersion gold ,OSP,lead free HASL	Min. Line Spacing	0.2mm
color	blue ,red ,green,black,yellow	price	\$0.1-\$10
applicable to	led,mobile phone,air conditioners,washing machines	Min. Line Width	0.2mm
character	Industrial Control pcb	Min. Hole Size	0.2mm
certificates	ISO9001,UL,RoHS,SGS	MOQ	10pcs
Q/CTN	10PCS-100PCS	weight	0.01kg -5kg
desigh type	client requirement		

Packaging & Delivery

Packaging Details	16 years professional OEM pcb board manufacturer
Delivery Detail	7-12days



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supplier

[MDI PCB Printed circuit board, Bare printed circuit board company](#)

Product Description

16 years professional OEM pcb board manufacture

item	2014		2015~2016		2017~2018	
	Volume	Sample	Volume	Sample	Volume	Sample
Layer count	32	42	38	44	42	48
Min Line/space (µm)	50/50	40/45	40/45	40/40	35/40	35/35
Min drill hole diameter (mm)	0.15	0.10	0.15	0.10	0.15	0.10
Aspect ratio of PTH	14:1	16:1	16:1	18:1	18:1	20:1
N+C+N	4+C+4	5+C+5	5+C+5	6+C+6	5+C+5	6+C+6
Any layer interconnection	5+2+5	6+2+6	5+2+5	6+2+6	5+2+5	6+2+6
Plate filling via	YES	--	YES	--	YES	--
Min. core thickness (exclude copper) (µm)	50	40	40	30	40	30
Min. Laser Drill diameter (µm)	75	65	65	50	50	40
Via on buried hole/stacked via	YES	--	YES	--	YES	--
Material	FR4, Megtron, Nelco, Rogers, Heavy Copper, etc.					
Embedded capacitor PCB	YES	--	YES	--	YES	--

Surface Process	Lead-free HASL, ENIG, OSP, Immersion silver, Immersion tin, Flash gold, Gold finger plating, Selective hard gold plating, Peelable solder mask, Carbon ink
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Our Team





Certifications

Packaging & Delivery

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[GOLDEN FINGER BOARD supplier](#)



FAQ

1. How do O-Leading ensure quality?

Our high quality standard is achieved with the following.

- 1.The process is strictly controlled under ISO 9001:2008 standards.
- 2.Extensive use of software in managing the production process
- 3.State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).
- 4.Dedicated quality assurance team with failure case analysis process
- 5.Continuous staff training and education

2. How do O-Leading keep your price competitive?

Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly. However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.

We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edge on cost and quality.

3. What kinds of boards can O-Leading process?

Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.

4. What data are needed for PCB production?

It is best to provide data in Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.

5. What's the typical process flow for multi-layer PCB?

Material cutting → Inner dry film → inner etching → Inner AOI → Multi-bond → Layer stack up
Pressing → Drilling → PTH → Panel Plating → Outer Dry Film → Pattern Plating → Outer etching →
Outer AOI → Solder Mask → Component Mark → Surface finish → Routing → E/T → Visual Inspection.